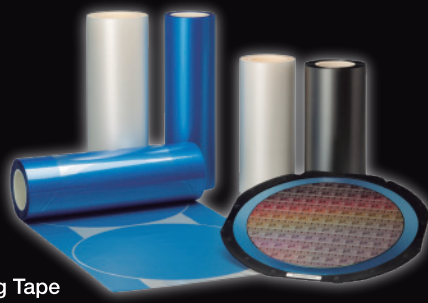


Tape X Equipment

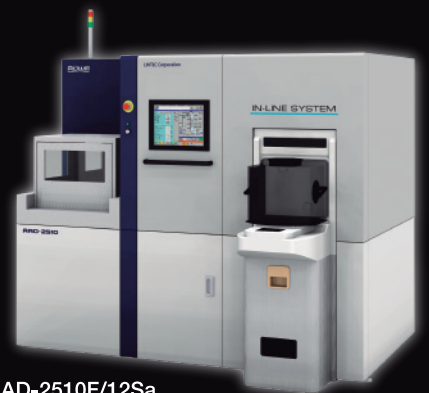
# Adwill

will give you the Advantage



Dicing Tape

Leveraging its comprehensive tape and equipment proposal capabilities, LINTEC is making innovative propositions for assembly and back-end process solutions that contribute to the production of thin, compact, high-density semiconductor packages as well as simpler manufacturing processes.



**RAD-2510F/12Sa**

300mm Fully-Automatic Multifunction Wafer Molder



**LINTEC Corporation**

Advanced Materials Operations

8th Fl., Bunkyo Garden Gate Tower, 1-1-1 Koishikawa, Bunkyo-ku, Tokyo 112-0002, Japan  
TEL.+81-3-3868-7737 FAX.+81-3-3868-7726

[www.adwill-global.com/en](http://www.adwill-global.com/en)